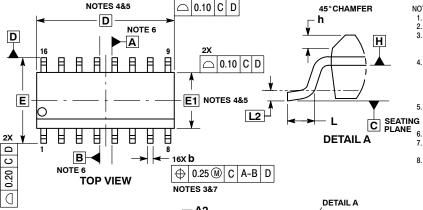




NOTE 8

SOIC-16 CASE 751BA **ISSUE A**

DATE 18 MAY 2015



△ 0.10 C

NOTES:

NOTE 7

END VIEW

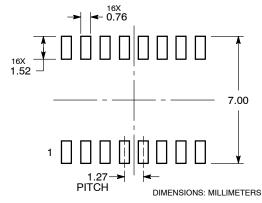
- LES:
 DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.004 mm IN EXCESS OF MAXIMUM MATERIAL CONDITION.
- DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.006 mm PER SIDE. DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.010 mm PER SIDE. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOT-THE PACKAGE 10P MAY BE SMALLER THAN THE PACKAGE BUITOM. DIMENSIONS D AND ET ARE DETERMINED AT THE OUTER-MOST EXTREMES OF THE PLASTIC BODY AT DATUM H.
 DIMENSIONS A AND B ARE TO BE DETERMINED AT DATUM H.
 DIMENSIONS A BAND & APPLY TO THE FLAT SECTION OF THE LEAD
 BETWEEN 0.10 TO 0.25 FROM THE LEAD TIP.
- A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

	MILLIMETERS		
DIM	MIN	MAX	
Α		1.75	
A1	0.10	0.25	
A2	1.25		
b	0.31	0.51	
С	0.10	0.25	
D	9.90 BSC		
Е	6.00 BSC		
E1	3.90 BSC		
е	1.27 BSC		
h	0.25	0.41	
L	0.40	1.27	
L2	0.25 BSC		

RECOMMENDED SOLDERING FOOTPRINT*

<⊟e l

SIDE VIEW



*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code = Assembly Location

WL = Wafer Lot Υ = Year WW = Work Week G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

DOCUMENT NUMBER:	98AON34919E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	SOIC-16		PAGE 1 OF 1

onsemi and Onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries, onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.